

**PATENT ASSIGNMENT**

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SUBMISSION TYPE:	NEW ASSIGNMENT
NATURE OF CONVEYANCE:	ASSIGNMENT
<b>CONVEYING PARTY DATA</b>	
<b>Name</b>	<b>Execution Date</b>
Chia-Hua Hsu	03/25/2009
Yi-Hua Lu	03/25/2009
Geng-Shing Jou	03/25/2009
Ting-Yao Chiu	03/25/2009
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<b>City:</b>	HsinChu
<b>State/Country:</b>	TAIWAN
<b>PROPERTY NUMBERS Total: 1</b>	
<b>Property Type</b>	<b>Number</b>
Application Number:	12411401
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Total Attachments: 2 source=592928#page1.tif source=592928#page2.tif	

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**PATENT**

### ASSIGNMENT OF INVENTION

In consideration of the payment by ASSIGNEE to ASSIGNOR of the sum of One Dollar (\$1.00), the receipt of which is hereby acknowledged, and for other good and valuable consideration.

**ASSIGNOR(S) (Inventors):**

Name: Chia-Hua Hsu Nationality: TWN

Name: Yi-Hua Lu Nationality: TWN

Name: Geng-Shing Jou Nationality: TWN

Name: Ting-Yao Chiu Nationality: TWN

Hereby sells, assigns and transfers to

**ASSIGNEE(S):**

Name: Realtek Semiconductor Corp.

Address: 2 Innovation Rd. II, Science Park, HsinChu 30076, Taiwan, R.O.C.

and the successors and assignees of the ASSIGNEE the entire right, title, and interest in and to any and all improvements which are disclosed in the invention entitled:

**"POWER MANAGING METHOD APPLIED TO A WIRELESS NETWORK APPARATUS AND POWER MANAGEMENT THEREOF"**

Which is found in :

- (a) + U.S. patent application executed on even date
- (b) \_\_\_\_\_ U.S. patent application executed on \_\_\_\_\_
- (c) \_\_\_\_\_ U.S. application serial no. \_\_\_\_\_
- (d) \_\_\_\_\_ patent no. \_\_\_\_\_ issued \_\_\_\_\_

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and, in and to, all Letters Patent to be obtained for said invention by the above application or any continuations, continuation-in-part, divisions, renewals, substitutes, or extensions thereof, and as to Letters Patent any reissue or re-examination thereof

ASSIGNOR hereby covenants that no assignment, sale, agreement or encumbrance has been or will be made or entered into which would conflict with this assignment;

ASSIGNOR further covenants that ASSIGNEE will, upon its request, be provided promptly with all pertinent facts and documents relating to said invention and said Letters Patent and legal equivalents as may be known and accessible to ASSIGNOR and will testify as to the same in any interference, litigation or proceeding related thereto and will promptly execute and deliver to ASSIGNEE or its legal representatives any and all papers, instruments or affidavits required to apply for, obtain, maintain, issue and enforce said application, said invention and said Letters Patent and said equivalents thereof which may be necessary or desirable to carry out the proposes thereof.

MAR 25 2009

IN WITNESS WHEREOF, We have hereunto set hand and seal this \_\_\_\_\_ (Date of signing). (請發明人務必簽署上列日期。)

(Type name of inventor)

Signature of INVENTOR

Chia-Hua Hsu

CHIA-Hua Hsu

Yi-Hua Lu

Yi-Hua Lu

Geng-Shing Jou

Jou, Geng-Shing

Ting-Yao Chiu

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